

SILICONE ADHESIVE TAD-O-SI-1C

thermally conductive 1 part / addition cure

TAD-O-SI-1C is an addition cure corrosion-free highly thermally conductive 1 part silicone adhesive. It cures at elevated temperature to a strong but still elastic rubber and exhibits excellent primerless adhesion to most surfaces. The adhesive features high thermal conductivity and a thixotropic rheology that will prevent slumping or flow during the process. It allows for being operated at temperatures up to 210°C and does not corrode copper or its alloys when fully cured. It is characterised by high resistance to water, acids, bases and most organic solvents and is especially suitable for applications where high thermal conductivity, adhesion, fast curing and controlled, precision application are essential.



Release 03 / 2020

PROPERTIES

- Thermal conductivity: 2.1 W/mK
- High bonding properties
- Heat cure
- Non corrosive
- Thixotropic rheology preventing flow during the process
- High operating temperatures up to 210°C
- Extraordinary chemical resistance and longterm stability

AVAILABILITY

- 1 kg jars
- 310 ml cartridges
- Bulk packaging options on request
- Optional with glass beads

APPLICATION EXAMPLES

- LED systems
- Processor cooling
- Memory chip assembly
- CPU boards

Technical Data Sheet

PROPERTY	UNIT	TAD-O-SI-1C
MATERIAL		
Colour		Grey
Specific Gravity	g/cm ³	2.18
Viscosity	Pas	140
Hardness	Shore A	56
Tensile Strength	MPa	2.20
Elongation at Break	%	105
Curing Time (3 mm @ 125°C / @ 100°C)	min	10 / 16
Shelf Life (from Date of Manufacturing, unopened, @ 10 – 30°C / @ < 10°C)	Months	2 / 12
Flammability	UL 94	HB (1.5 mm, V0 6.0 mm)
RoHS Conformity	2015 / 863 / EU	Yes
THERMAL		
Thermal Conductivity	W/mK	2.10
Coefficient of Thermal Expansion Volumetric	x 10 ⁻⁶ /K	586
Coefficient of Thermal Expansion Linear	x 10 ⁻⁶ /K	195
Operating Temperature Range	°C	- 50 to + 210
ELECTRICAL		
Dielectric Strength	kV/mm	> 18
Volume Resistivity	Ohm - cm	> 3.5 x 10 ¹³

All data without warranty and subject to change. Please contact us for further data and information.

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